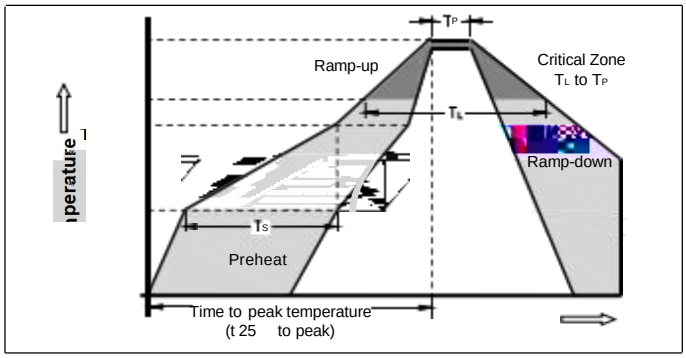
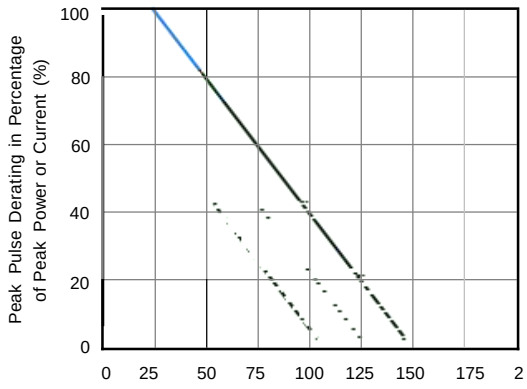
	Contact manufacturer
	Epoxy encapsulated
	Silver plated leads, solderable per MIL-STD-750, Method 2026



		Lead–free assembly
		150°C
		200°C
		60 -180 Seconds
		3°C/second max
		3°C/second max
		217°C
		60 -150 Seconds
		260 +0/-5°C
		20 -40 Seconds
		6°C/second max
		8 minutes Max
		280°C

	265°C
	10 seconds
	1 time



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